

Notice for Issuing of Technical Newsletter



Information about Pad in Transfer Arm 2 Section

Information about Pad Inquiries

This notice has been issued for customers using porous pads in the applicable equipment models below.

Proposals for new pads have been prepared for customers currently having issues with small scratches on the wafer after transferring the wafer via the transfer arm 2 section.

The details are explained in the Technical Newsletter (tn12018-0010e).

If you would like more information, please contact your DISCO sales representative or your DISCO customer engineer.

Applicable Models

DFG8540/8560

DGP8760

DFP8140/8160